

PATENT ASSIGNMENT COVER SHEET

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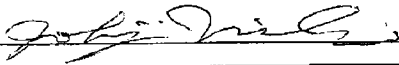
SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JOHJI NISHIO	01/21/2015
RYOSUKE IJIMA	01/21/2015
KAZUTO TAKAO	01/21/2015
TAKASHI SHINOHE	01/21/2015
RECEIVING PARTY DATA	
Name:	KABUSHIKI KAISHA TOSHIBA
Street Address:	1-1, Shibaura 1-chome, Minato-Ku
City:	Tokyo
State/Country:	Japan
Postal Code:	105-8001
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14614699
CORRESPONDENCE DATA	
Fax Number:	(703)413-2220
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(703) 413-3000
Email:	ehasan@oblon.com
Correspondent Name:	OBLON, ET AL.
Address Line 1:	1940 DUKE STREET
Address Line 4:	ALEXANDRIA, VIRGINIA 22314
ATTORNEY DOCKET NUMBER:	448458US20RD
NAME OF SUBMITTER:	EMEL HASAN
SIGNATURE:	/Emel Hasan/
DATE SIGNED:	02/05/2015
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 4	
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**DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN
APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE**

Title of Invention	METHOD FOR FABRICATING SEMICONDUCTOR SUBSTRATE, SEMICONDUCTOR SUBSTRATE, AND SEMICONDUCTOR DEVICE
As the below named inventor, I hereby declare that: This declaration ☒ The attached application, or is directed to: ☐ United States application or PCT international application number _____ filed on _____ The above-identified application was made or authorized to be made by me. I believe that I am the original inventor or an original joint inventor of a claimed invention in the application. WHEREAS, <u>Kabushiki Kaisha Toshiba</u> (hereinafter referred to as "ASSIGNEE") having places of business at: <u>1-1 Shibaura 1-chome, Minato-ku, Tokyo 105-8001 Japan</u>, is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefore in the United States and its territorial possessions and in any and all foreign countries; NOW, THEREFORE, in consideration of the sum of FIVE DOLLARS (\$5.00), the receipt whereof is hereby acknowledged, and for other good and valuable consideration, I, by these presents do sell, assign and transfer unto said ASSIGNEE, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries (including the right to claim priority under the terms of the International Convention and other relevant International Treaties and Arrangements from the aforesaid application) and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations, substitutions and renewals thereof. I hereby authorize and request the Patent Office Officials in the United States and its territorial possessions and any and all foreign countries to issue any and all of said Letters Patent, when granted, to said ASSIGNEE as the assignee of my entire right, title and interest in and to the same, for the sole use and behoof of said ASSIGNEE, its (his) successors and assigns, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held by me had this Assignment and sale not been made. Further, I agree that I will communicate to said ASSIGNEE or its (his) representatives any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said ASSIGNEE, make all rightful oaths, and, generally do everything possible to aid said ASSIGNEE, its (his) successors and assigns, to obtain and enforce proper protection for said invention in the United States and its territorial possessions and in any and all foreign countries. I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.	
LEGAL NAME OF INVENTOR	
Inventor: <u>Johji NISHIO</u>	Date: <u>Jan. 21, 2015</u>
Signature: <u></u>	

OBLON, SPIVAK, McCLELLAND, MAIER & NEUSTADT, L.L.P.
ATTORNEYS AT LAW
1940 DUKE STREET
ALEXANDRIA, VIRGINIA 22314

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LEGAL NAME OF INVENTOR	
Inventor: <u>Ryosuke IJIMA</u>	Date: <u>Jan 21, 2015</u>
Signature: <u>Ryosuke Ijima</u>	

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LEGAL NAME OF INVENTOR	
Inventor: <u>Kazuto TAKAO</u>	Date: <u>Jan. 21, 2015</u>
Signature: <u>Kazuto Takao</u>	

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LEGAL NAME OF INVENTOR	
Inventor: <u>Takashi SHINOHE</u>	Date: <u>Jan. 21, 2015</u>
Signature: <u>Takashi Shinohe</u>	

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